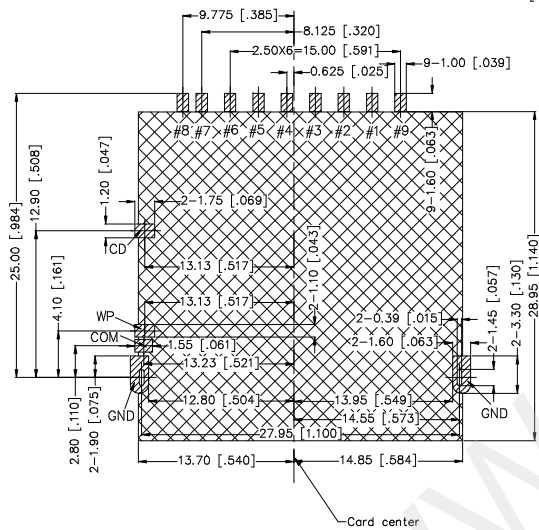
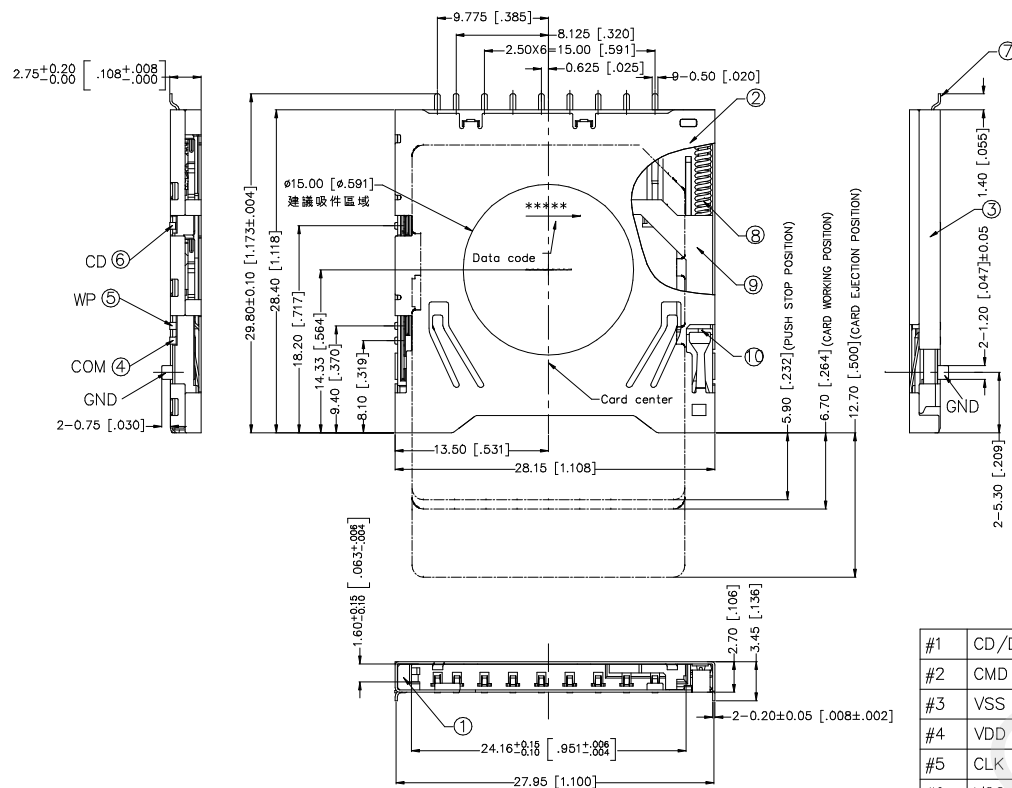




RECOMMENDED P.C.B. LAYOUT

PCB DIMENSION DEFAULT TOLERANCE: ± 0.05

1. : RECOMMENDED SOLDER PAD AREA
2.  : TRACE KEEP OUT AREA

#1	CD/DAT3
#2	CMD
#3	VSS
#4	VDD
#5	CLK
#6	VSS
#7	DAT0
#8	DATE1
#9	DATE2

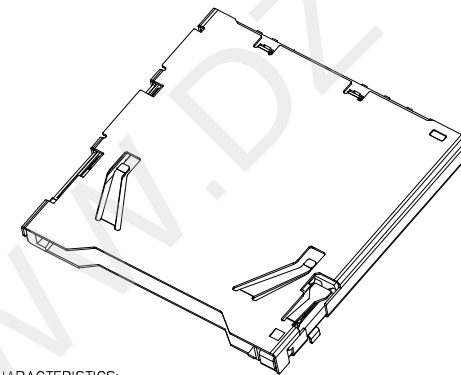
SD SIGNAL PIN DEFINE



WP: WRITE PROTECT SWITCH CONTACT
COM: COMMON SWITCH CONTACT
CD: CARD DETECT SWITCH CONTACT

Switch Operation Diagram

ELECTRIC FUNCTION	WRITE PROTECT SWITCH				CARD DETECT SWITCH	
	WRITE UNABLE		WRITE ENABLE			
CARD NAME	MMC	SD	MMC	SD	MMC	SD
WITHOUT CARD		OPEN		OPEN	OPEN	OPEN
CARD INSERTED		OPEN		CLOSE	CLOSE	CLOSE
SWITCH DIAGRAM	WP ——— COM				COM ——— CD	



SPCIFICATION

1. ELECTRICAL CHARACTERISTICS:
 - 1-1. CONTACT CURRENT RATING: 0.5A MAX.
 - 1-2. CONTACT RESISTANCE: 100 mOHMS MAX.
 - 1-3. OPERATING VOLTAGE: 3.3V.
TESTING VOLTAGE: 500V AC 1 MINUTE.
 - 1-4. INSULATION RESISTANCE:
INITIAL: 1000 MOHMS MIN.
AFTER TEST: 100 MOHMS MIN.
 - 1-5. OPERATING CURRENT: 0.1A MAX
2. MECHANICAL CHARACTERISTICS:
 - 2-1. TOTAL MATING FORCE: 40N MAX.
 - 2-3. DURABILITY : 10000 CYCLES.
3. ENVIRONMENT CHARACTERISTICS:
 - 3-1. OPERATING TEMPERATURE: -25℃~85℃
 - 3-2. STORAGE TEMPERATURE: -40℃~85℃
4. CARD OPERATION GUIDE:
 - 4-1. COMPATIBLE CARD: SD&SDIO&MMC CARD
 - 4-2. CARD INSERT DIRECTION:
THE CARD SIDE WITH ELECTRIC PAD SHOULD BE AGAINST TOP SHIELD
5. RECOMMENDED IR REFLOW PORCESS PEAK TEMPERATURE: 250±5℃, TIME 10s MAX
6. ALL SMT CONTACTS AND PADS CO-PLANARITY: 0.10mm MAX
7. DON'T PERMIT TO BE PROCEEDED SMT RE-FLOW PROCESS WHEN
PUSH-PUSH FEATURE IS IN WORKING POSITION

10	CAM FOLLOWER	1	SUS304		
9	SLIDER	1	HTN	COLOR: BLACK	
8	SPRING	1	SWP		
7	SIGNAL CONTACT	9	PH/BR	60-100% Ni UNDERPLATING OVER ALL 100-200% LEAD FREE TIN ALLOY PLATING AT SOLDERING AREA 30/1" Min Au OR 30/2" Min Pd/Ni-5-30/7 Au PLATING AT CONTACT AREA OR 1/8" Min Au PLATING AT CONTACT AREA	
6	DETECT SWITCH CONTACT	1	PH/BR		
5	WRITE PROTECT SWITCH CONTACT	1	PH/BR	60-100% Ni UNDERPLATING OVER ALL 1/8" Min Au PLATING AT SOLDERING AREA 1/8" Min Au PLATING AT CONTACT AREA	
4	COMMON SWITCH CONTACT	1	PH/BR		
3	BOTTOM SHELL	1	SUS304	30-100/Min Ni UNDERPLATING OVER ALL 1/8" Min Au PLATING AT SOLDERING AREA	
2	TOP SHELL	1	SUS301	CLEAN	
1	HOUSING	1	LCP	COLOR: BLACK	
ITEM	DESCRIPTION	Q'TY	MATERIAL	FINISH	REMARK



深圳市华宇创精密电子有限公司

TOLERANCE:		DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME:	
X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X: ±2° X.X° ±0.5°				SD PUSH 2.7H	
 UNIT: mm [inch]		CHECKED BY:	DATE :	PART NO.	HYC67-SD12-270
		马跃	2014-02-23	MOLD NO.	
				DRAW NO:	HYC-2203031041
SCALE:1:1	SIZE: A4	APPROVED BY:	DATE :	SHEET NO.	1 OF 1
		邱敏	2014-02-23		